

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the paragraph beginning at page 5, line 7 with the following amended paragraph:**

In the present embodiment a silicon substrate is used as the substrate 10. As is shown in Fig. 2A, insulating layers 11 formed by a ~~silicone~~ silicon oxide film having a thickness of several  $\mu\text{m}$  or less, and preferably of approximately  $1\mu\text{m}$ , are formed on both main surfaces A and B of the substrate 10.

**Please replace the paragraph beginning at page 6, line 12 with the following amended paragraph:**

Next, as is shown in Fig. 2C, a protective member 20 is bonded to the main surface A of the substrate 10, so that the electroconductive thin film 12 is held by the protective member 20. Any member that has a flat surface portion and is able to hold the electroconductive thin film 12 by this flat surface portion may be used as the protective member 20 and examples thereof include a glass substrate, semiconductor substrates such as silicon, ceramic substrates, and plastic substrates. It is preferable that the protective member 20 is bonded to the main surface A of the substrate 10 using a hot melt adhesive, an ultraviolet hardening adhesive or the like. A hot melt adhesive is particularly preferable as it allows a protective member 20 that has been attached to the substrate 10 to be removed simply by heating the substrate 10. The protective member may be removed subsequent to the insertion of the electroconductive substance, as described below. Note that it is sufficient if the protective member 20 holds at least the

micropore formation portion of the electroconductive thin film 12. However, as is shown in Fig. 2C, it is preferable that the protective member 20 holds the entire electroconductive thin film 12.

**Please replace the paragraph beginning at page 7, line 10 with the following amended paragraph:**

If an electroconductive substance 14 such as Cu paste is inserted using a printing method then the printing pressure is set at a level sufficient to ensure an electrical connection between the electroconductive thin film 12 and the electroconductive substance 14. In the present embodiment, because one surface of the electroconductive thin film 12 is held by the protective member 20, even if the electroconductive substance 14 is inserted into the micropore 13 at high pressure, there is no breakage of the electroconductive thin film 12. The pressure at a side of the electroconductive film facing the protective member may be higher than the pressure on a side of the electroconductive film facing the first aperture.